

Title (en)

LAMINATED ASSEMBLY COMPRISING RADIO-FREQUENCY INTERFACE BOARD

Title (de)

LAMINIERTE ANORDNUNG MIT HOCHFREQUENZSCHNITTSTELLENPLATTE

Title (fr)

ENSEMBLE STRATIFIÉ COMPRENANT UNE CARTE D'INTERFACE RADIOFRÉQUENCE

Publication

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Application

EP 21734159 A 20210623

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Abstract (en)

[origin: WO2022078638A1] The present invention discloses an improved RF interface board and a laminated assembly having a RF interface board having an inner and an outer part, comprising a dielectric support having a first and a second surfaces and at least a first and a second RF transmission strips disposed on the dielectric support; the first and the second RF transmission strips are electrically isolated from each other; the first and the second RF transmission strips are configured to be connected to a connector at the outer part and are each configured to be connected to a different conductive element at the inner part; the first RF transmission strip is on the first surface. The present invention discloses the associated method and use.

IPC 8 full level

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See references of WO 2022078638A1

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